

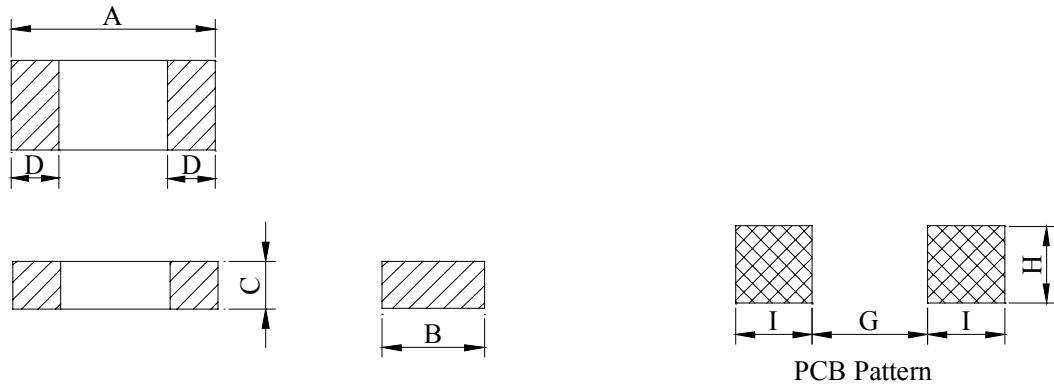
SPECIFICATION FOR APPROVAL

REF :

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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO.	MB1608□□□□5□
		ABC'S ITEM NO.	

I . CONFIGURATION & DIMENSIONS :



Unit : m/m

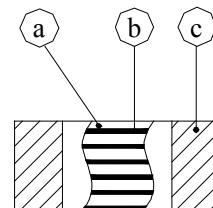
Series	A	B	C	D	G	H	I
MB1608	1.60±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.7	0.7	0.7

II . SCHEMATIC DIAGRAM :



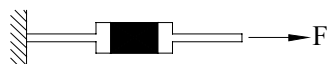
III . MATERIALS :

- a . Body : Ferrite
- b . Internal conductor : Silver or Ag / Pd
- c . Terminal electrode : Ag/Ni/Sn (Lead content 100ppm max.)
- d . Remark : Lead content 1600ppm typ. include ferrite



IV . GENERAL SPECIFICATION :

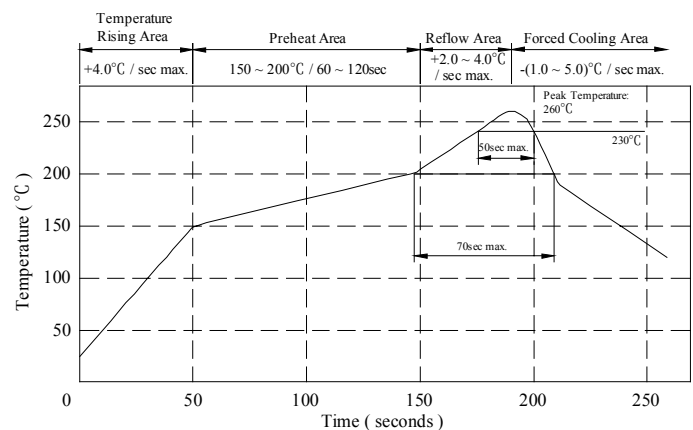
- a . Storage temp. : -40 ---- +105°C
- b . Operating temp. : -25 ---- +85°C
- c . Terminal Strength :



Type	F (kgf)	time (sec)
MB1608	0.5	30±5

- d . Solderability : Preheat : 150±25°C for 60 seconds
Solder : Sn96.5 / Ag3 / Cu0.5
or equivalent
Solder temp. : 260±5°C
Flux : Rosin
Dip time : 4±1 seconds

Peak Temp : 260°C max.
Max time above 230°C : 50sec max.
Max time above 200°C : 70sec max.



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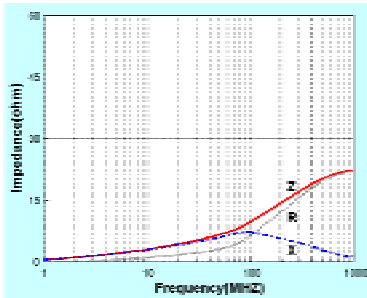
V . ELECTRICAL CHARACTERISTICS :

DWG No.	Impedance (Ω)	Z Test Freq. (MHz)	RDC (Ω) max.	Ir (mA) max.
MB1608100Y5□	10.0 $\pm$ 25%	100	0.02	2000
MB1608300Y5□	30.0 $\pm$ 25%	100	0.03	2000
MB1608600Y5□	60.0 $\pm$ 25%	100	0.03	2000
MB1608121Y5□	120.0 $\pm$ 25%	100	0.10	1000
MB1608221Y5□	220.0 $\pm$ 25%	100	0.15	800
MB1608301Y5□	300.0 $\pm$ 25%	100	0.20	600

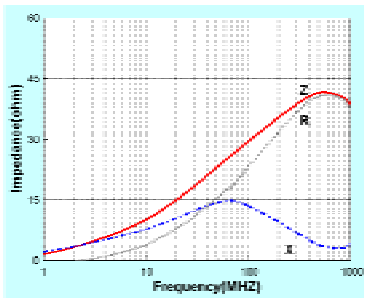
1). □ : Packaging Information... **A** Bulk **B** Taping Reel

VI . IMPEDANCE VS. FREQUENCY CHARACTERISTICS :

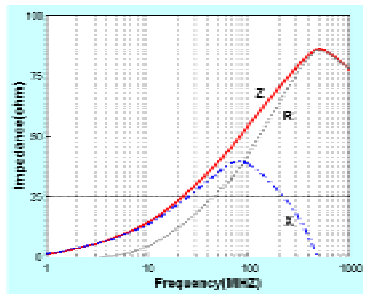
MB1608-100



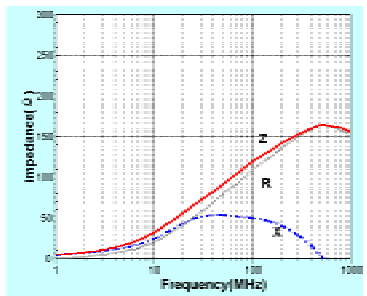
MB1608-300



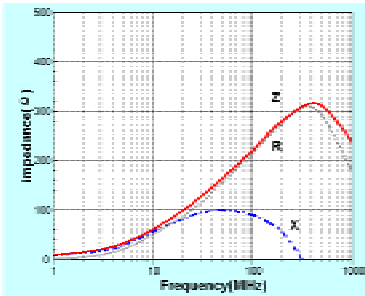
MB1608-600



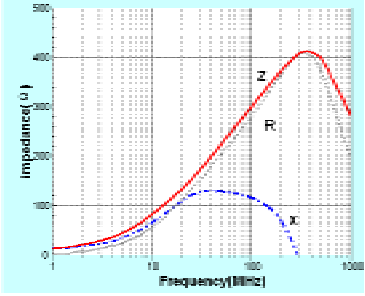
MB1608-121



MB1608-221



MB1608-301



SPECIFICATION FOR APPROVAL

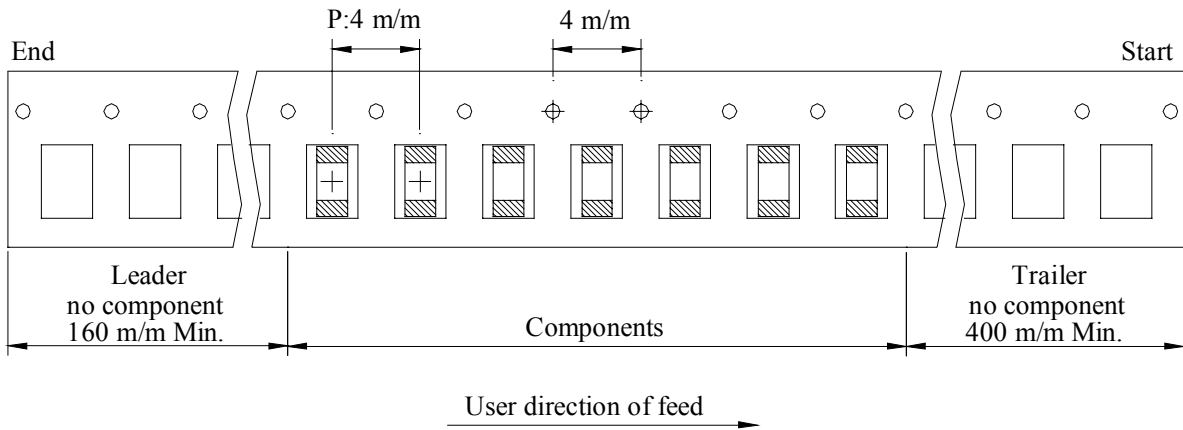
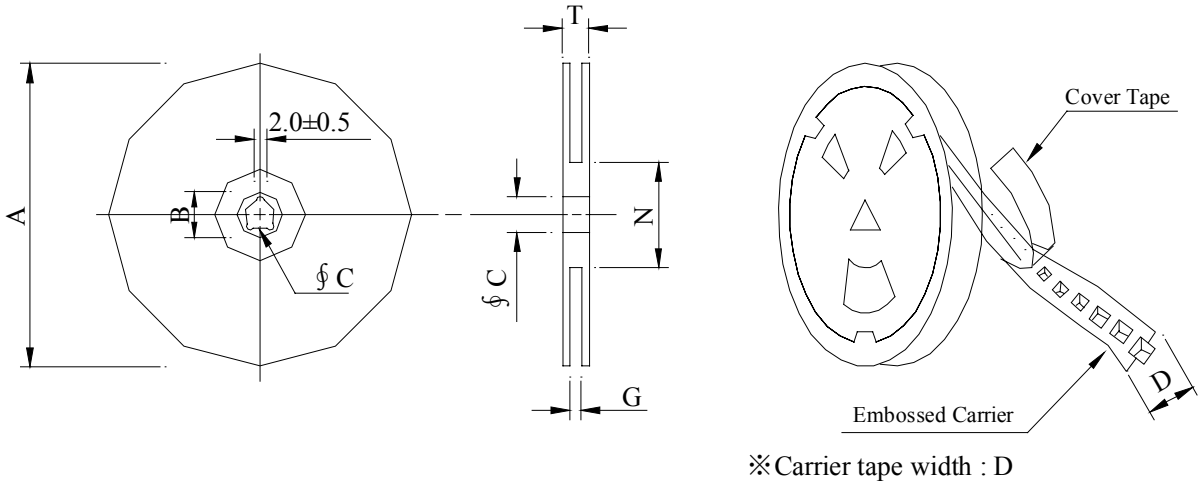
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VII . PACKAGING INFORMATION

(1) Confihuration



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21 ± 0.8	13	8	10^{+0}	50^{-0}	12.5

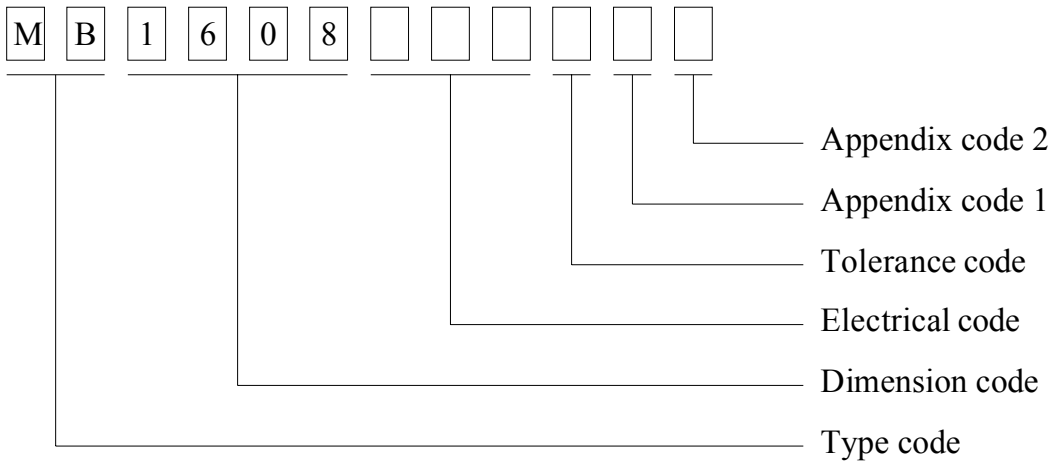
(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY(pcs)	G.W. (Kg)	Size (cm)
MB1608	4,000	90	07 - 08	200,000	7.0	41 x 39 x 22

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VIII . DWG EXPRESSION :



- Appendix code 1 : S : Standard products
- A K, M R, T Z : Special products
- L : Standard Lead Free products
- 1 ~ 9 : Special Lead Free products

Appendix code 2 :

Code	Inner package	Inner package Q'TY	Remark
A	Empty	Empty	
B	T / R (Reel package)	4000 pcs	